

# RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1669	May-96	9615 B3	OMEDATA	DD548381ABG	1.2μ OX/NI EEPROM	08 SOIC 200

## STRESS/JOB NO.

## READPOINT (Sample Size/No. of Fails)

Preconditioning (P/C):  
HTC Vapor Phase  
P-17536

<u>Electrical</u>	<u>Cum %</u>
233/0	0.0%

Infant / High Voltage Life \*\*  
125°C, 7.0 V.  
P-17799, P-17890

<u>48 Hr</u>	<u>336 Hr</u>	<u>1KHr</u>	<u>*Failure Rate</u>
231/0	75/0	75/0	31 Fits

\*Chi Squared Method, 60% C. L., 55°C & 5.5V; Temperature Derating: Ea = 0.7 ev; Voltage Derating B = 1.0  
\*\* with Write Cycle Program stress = 60~/hr/cell

Temp Cycle  
-55°C to +125°C  
P-17891

<u>300 ~</u>	<u>1K ~</u>	<u>Cum %</u>
39/0	39/0	0.0%

Biased Moisture  
85°C/85% RH, 5.5 V.  
P-17892

<u>274 Hr</u>	<u>959 Hr</u>	<u>Cum %</u>
77/0	77/0	0.0%

Storage Life  
150°C, No bias  
P-17893

<u>336 Hr</u>	<u>1KHr</u>	<u>Cum %</u>
38/0	38/0	0.0%

## Failure Mode

## Failure Analysis